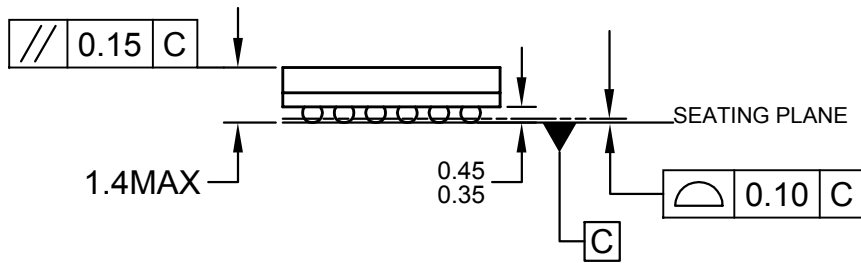
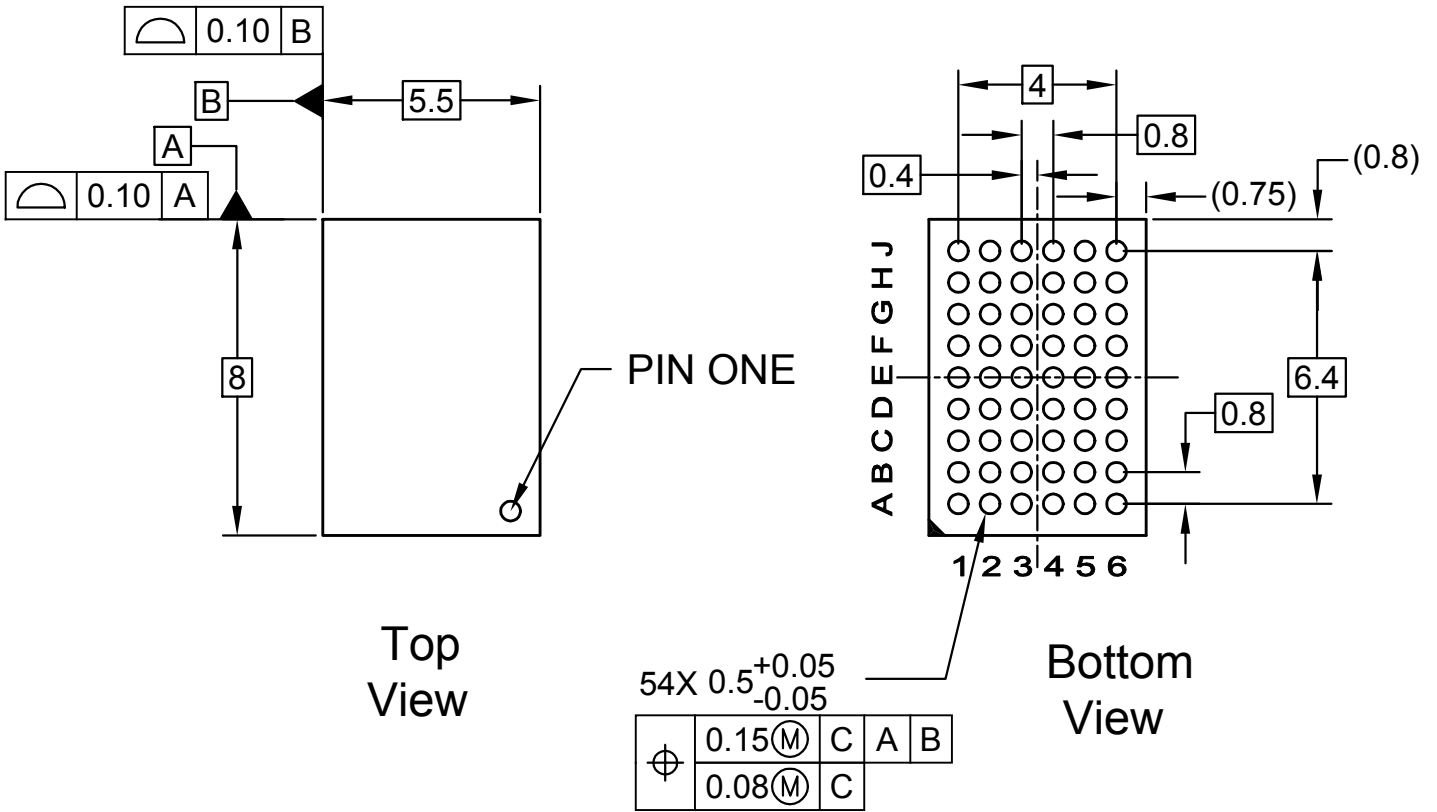


REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
0	ORIGINAL DRAWING RELEASED TO MARKETING	NA	11/11/99	H.ALLEN
1	REVISED OVERALL PACKAGE LENGTH, ADDED BALL OFFSET	NA	1/6/00	H.Allen
A	ADDED LANDPATTERN RECOMMENDATION RELEASED TO MARKETING	NA	1/26/00	H.ALLEN
B	ADDED Ball position tolerances	NA	8/24/00	J Kingsbury
C	JEDEC reference Changed to (MO-205) RELEASE TO DOCUMENT CONTROL	ECN-MKT-BGA54revC	05-09-01	J Kingsbury
D	Changed Revision Level only	ECN-MKT-BGA54AreVD	06-07-01	J Kingsbury



NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC MO-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

APPROVALS		DATE	FAIRCHILD 333 Western Ave. SEMICONDUCTOR S. Portland, Maine
HT KOAY		22-12-98	
DFTG. CHK	J.Kingsbury	01-24-01	54BALL, FBGA, JEDEC MO-205, 5.5MM WIDE
ENGR. CHK	J.Kingsbury	01-24-01	
PROJECTION		SCALE	SIZE
		N/A	N/A
		DRAWING NUMBER	REV
		MKT-BGA54A	D
		DO NOT SCALE DRAWING	SHEET 1 of 1

BGA54AreVD